

PRODUCT DESCRIPTION



Tflex™ SF16 is an innovative, ultra-high performing thermal material in Laird's gap filler portfolio. This non-silicone material measures 16 W/m•K in thermal conductivity and has excellent deflection properties which provides minimal pressure on components during deflection. Very little pressure is required to reach the lowest possible thermal resistance.

FEATURES AND BENEFITS

- Non-silicone formulation
- Exceptionally low thermal resistance
- Low peak and residual pressure
- Excellent surface wetting for low contact resistance
- Thermoplastic matrix softens with application heat, further lowering contact resistance
- Naturally tacky surfaces
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH

TYPICAL PROPERTIES

PROPERTIES	TYPICAL VALUE	TEST METHOD
Construction & Composition	Ceramic filled non-silicone thermoplastic	N/A
Color	Light Grey	Visual
Thickness Range	0.5mm – 5mm	N/A
Thermal Conductivity	16 W/m•K	Hot Disk
Density	3.09 g/cc	Helium Pycnometer
Thermal Resistance(1.0mm)	0.55 °C•cm ² /W	ASTM D5470
@ 30% deflection, 50 °C	0.085 °C •in ² /W	
Temperature Range	-40°C to 125°C	Laird Test Method
Hardness Shore 00 (3 second)	40 (1mm-5mm) 62 (0.5mm-0.75mm)	ASTM D2240
Hardness Shore 00 (30 second)	8 (1mm-5mm) 39 (0.5mm-0.75mm)	ASTM D2240
Outgassing (TML%)	0.60	ASTM E595
Outgassing (CVCM %)	0.22	ASTM E595
Dielectric Constant @1MHz	TBD	ASTM D150
Volume Resistivity (Ω cm)	10 ¹⁴	ASTM D257
UL Flammability Rating	V-0 (pending)	UL 94

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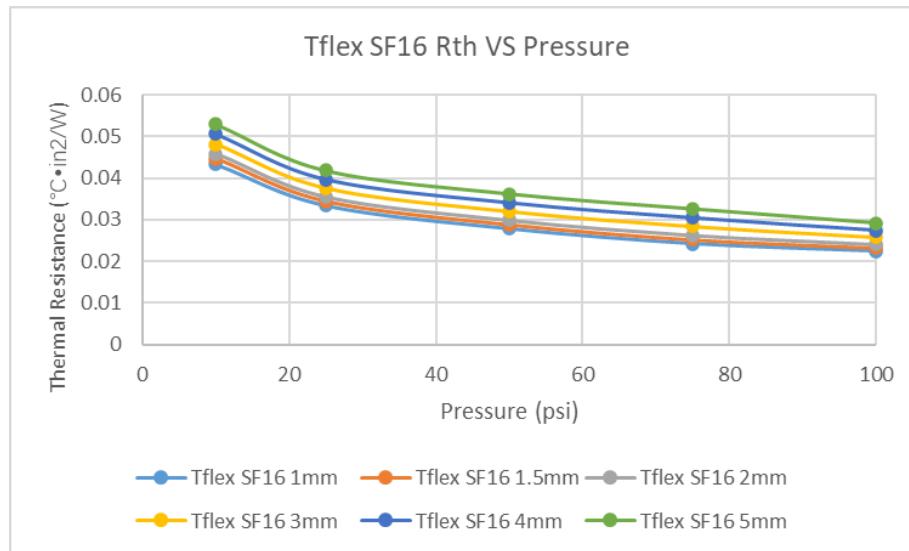
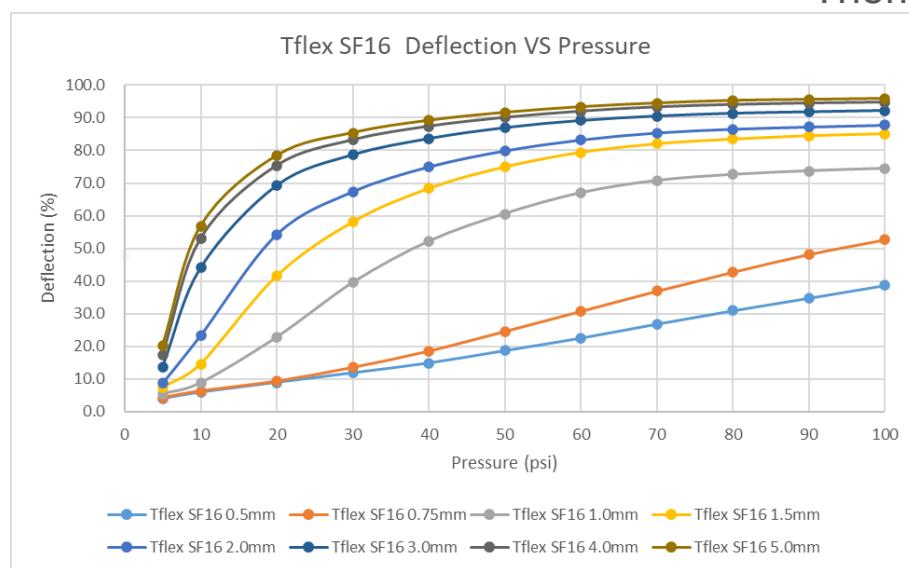
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www.laird.com



THR-DS-Tflex SF16

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AVAILABILITY

- 0.5 mm (0.020") to 5.0 mm (0.200") thick material available in 0.25mm (0.010") increments
- Available in standard sheet sizes of 18" x 18" and 9" x 9" or custom converted die cut parts
- DF option available to decrease tack on one side
- A1 option available to increase adhesion on one side

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. SF16 is a non-silicone 16 W/m•K material. Thickness of the sheet in mm is listed after the material name.

EXAMPLES:

- Tflex™ SF16,1.00 = 1.00mm thick Tflex SF16 material
- Tflex™ SF16DF,1.00 = 1.00mm thick Tflex SF16 material with only one side tacky

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